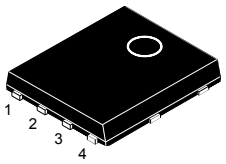
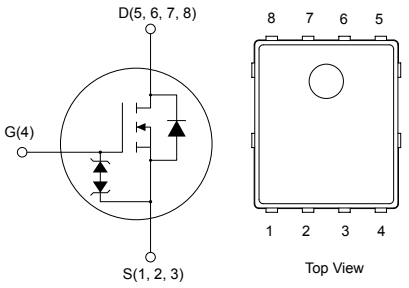
N-channel 600 V, 390 mΩ typ., 6.4 A MDmesh™ M6 Power MOSFET in a PowerFLAT™ 5x6 HV package



PowerFLAT™ 5x6 HV



Features

Order code	V_{DS} @ T_{Jmax}	$R_{DS(on)}$ max.	I_D	P_{TOT}
STL12N60M6	650 V	490 mΩ	6.4 A	48 W

- Reduced switching losses
- Lower $R_{DS(on)}$ per area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications
- LLC converters
- Boost PFC converters

Description

The new MDmesh™ M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs.
STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent $R_{DS(on)}$ per area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum end-application efficiency.

Product status
STL12N60M6

Product summary	
Order code	STL12N60M6
Marking	12N60M6
Package	PowerFLAT™ 5x6 HV
Packing	Tape and Reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_{case} = 25 °C	6.4	A
	Drain current (continuous) at T_{case} = 100 °C	4	
I_{DM} (1)	Drain current (pulsed)	24	A
P_{TOT}	Total power dissipation at T_{case} = 25 °C	48	W
I_{AR} (2)	Avalanche current, repetitive or not repetitive	1.8	A
E_{AS} (3)	Single pulse avalanche energy	130	mJ
dv/dt(4)	Peak diode recovery voltage slope	15	V/ns
dv/dt(5)	MOSFET dv/dt ruggedness	100	
T_{stg}	Storage temperature range	-55 to 150	°C
T_j	Operating junction temperature range		

1. *Pulse width is limited by safe operating area.*
2. *Pulse width limited by T_{jmax}.*
3. *starting T_j = 25 °C, I_D = I_{AR}, V_{DD} = 50 V.*
4. *I_{SD} ≤ 6.4 A, di/dt = 400 A/µs; V_{DS} peak < $V_{(BR)DSS}$, V_{DD} = 400 V.*
5. *V_{DS} ≤ 480 V.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	2.6	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	50	

1. *When mounted on a 1-inch² FR-4, 2 Oz copper board.*

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 3. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	600			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 600 V			1	µA
		V_{GS} = 0 V, V_{DS} = 600 V, T_{case} = 125 °C (1)			100	
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3.25	4	4.75	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 3.2 A		390	490	mΩ

1. *Defined by design, not subject to production test.*

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, f = 1 MHz, V_{GS} = 0 V	-	452	-	pF
C_{oss}	Output capacitance		-	39.4	-	
C_{rss}	Reverse transfer capacitance		-	4.5	-	
$C_{oss\ eq.}$ (1)	Equivalent output capacitance	V_{DS} = 0 to 480 V, V_{GS} = 0 V	-	85	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz, I_D = 0 A	-	6	-	Ω
Q_g	Total gate charge	V_{DD} = 480 V, I_D = 9 A, V_{GS} = 0 to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	12.3	-	nC
Q_{gs}	Gate-source charge		-	3	-	
Q_{gd}	Gate-drain charge		-	6.5	-	

1. *$C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 300 V, I_D = 4.5 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	16.6	-	ns
t_r	Rise time		-	6.4	-	
$t_{d(off)}$	Turn-off delay time		-	23.9	-	
t_f	Fall time		-	9.9	-	

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		6.4	A
I_{SDM} (1)	Source-drain current (pulsed)		-		24	A
V_{SD} (2)	Forward on voltage	V_{GS} = 0 V, I_{SD} = 6.4 A	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 9 A, di/dt = 100 A/µs, V_{DD} = 60 V (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	174		ns
Q_{rr}	Reverse recovery charge		-	1.27		µC
I_{RRM}	Reverse recovery current		-	14.6		A
t_{rr}	Reverse recovery time	I_{SD} = 9 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_j = 150 °C (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	241		ns
Q_{rr}	Reverse recovery charge		-	1.9		µC
I_{RRM}	Reverse recovery current		-	15.6		A

1. *Pulse width is limited by safe operating area.*
2. *Pulse test: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics curves

Figure 1. Safe operating area

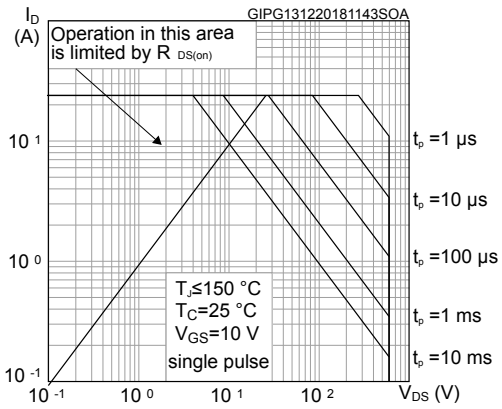


Figure 2. Thermal impedance

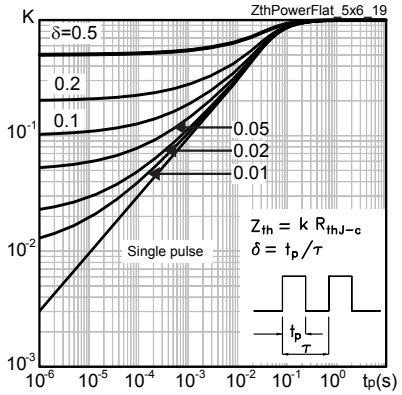


Figure 3. Output characteristics

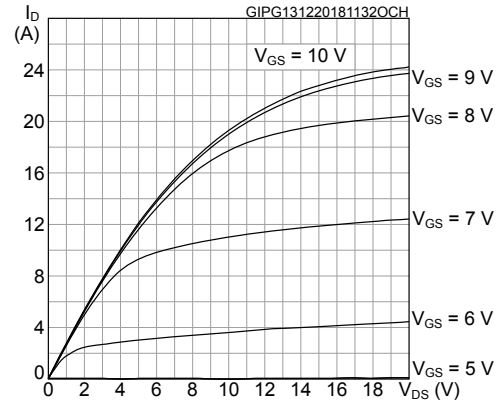


Figure 4. Transfer characteristics

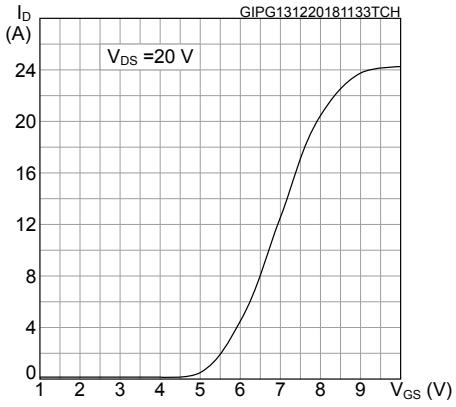


Figure 5. Gate charge vs gate-source voltage

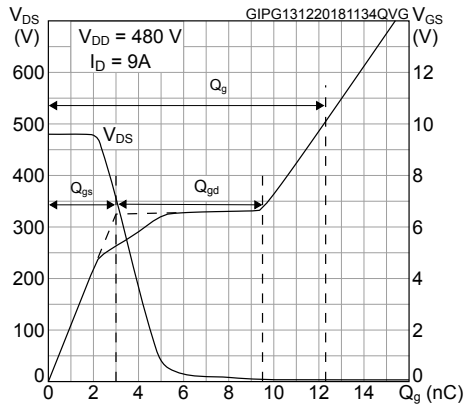


Figure 6. Static drain-source on-resistance

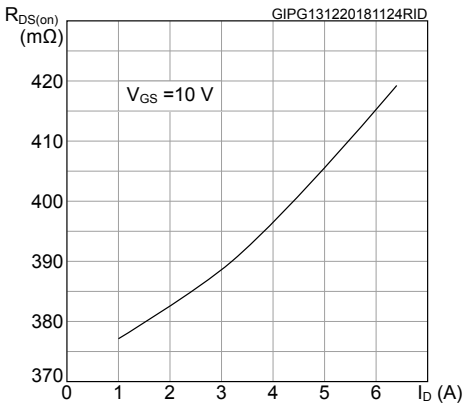


Figure 7. Capacitance variations

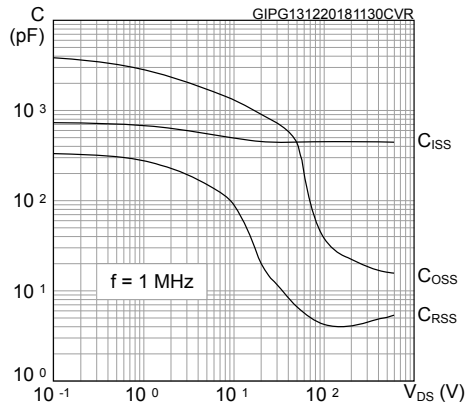


Figure 8. Output capacitance stored energy

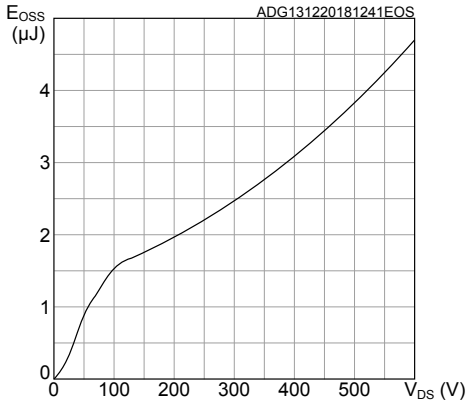


Figure 9. Normalized gate threshold voltage vs temperature

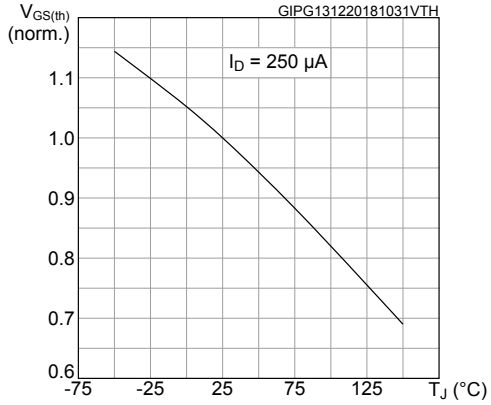


Figure 10. Normalized on-resistance vs temperature

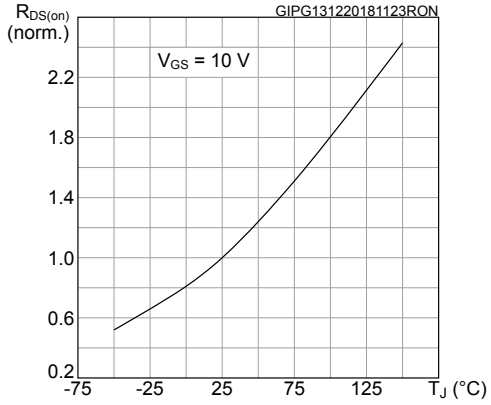


Figure 11. Normalized $V_{(BR)DSS}$ vs temperature

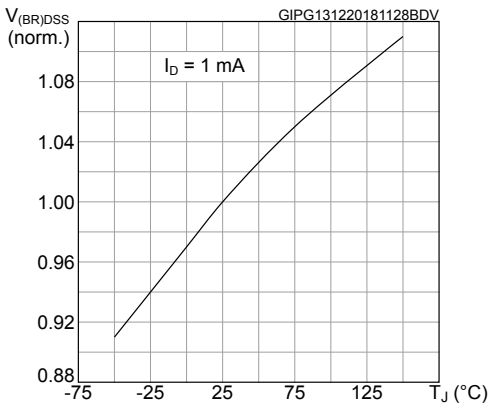
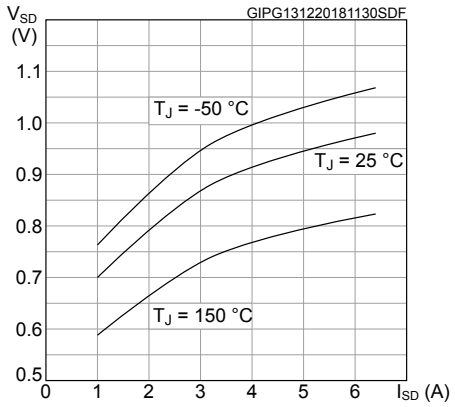


Figure 12. Source-drain diode forward characteristics



3 Test circuits

Figure 13. Test circuit for resistive load switching times

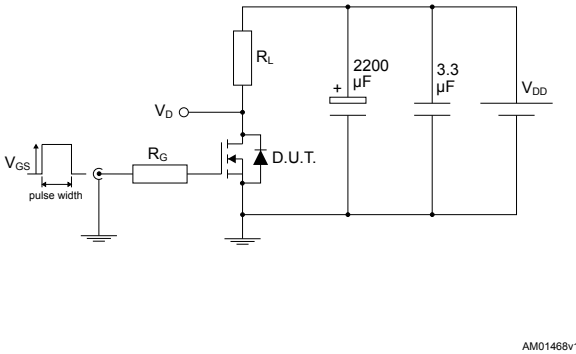


Figure 14. Test circuit for gate charge behavior

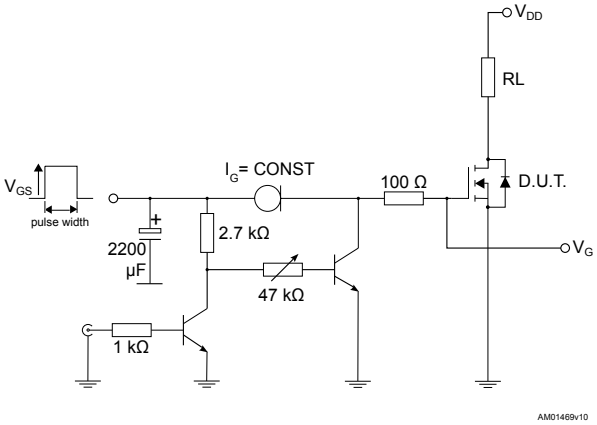


Figure 15. Test circuit for inductive load switching and diode recovery times

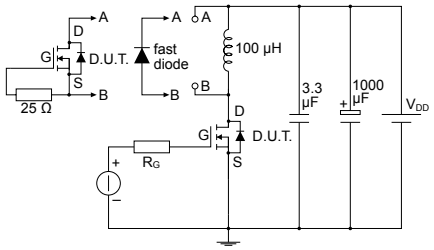


Figure 16. Unclamped inductive load test circuit

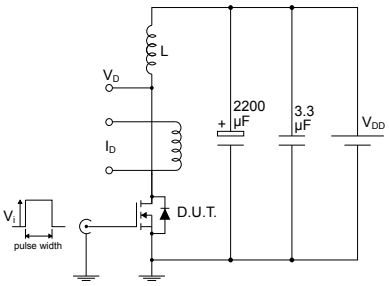


Figure 17. Unclamped inductive waveform

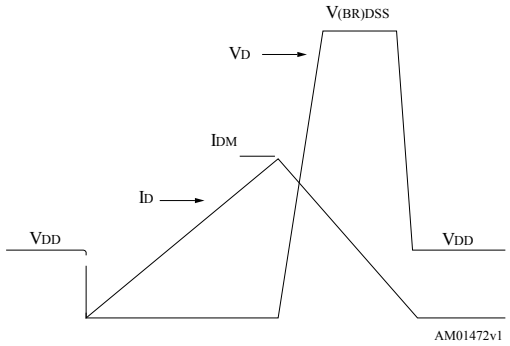
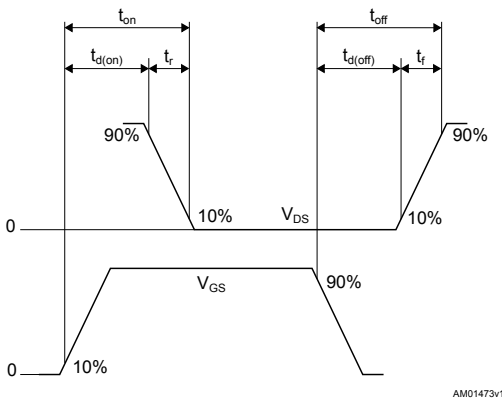


Figure 18. Switching time waveform

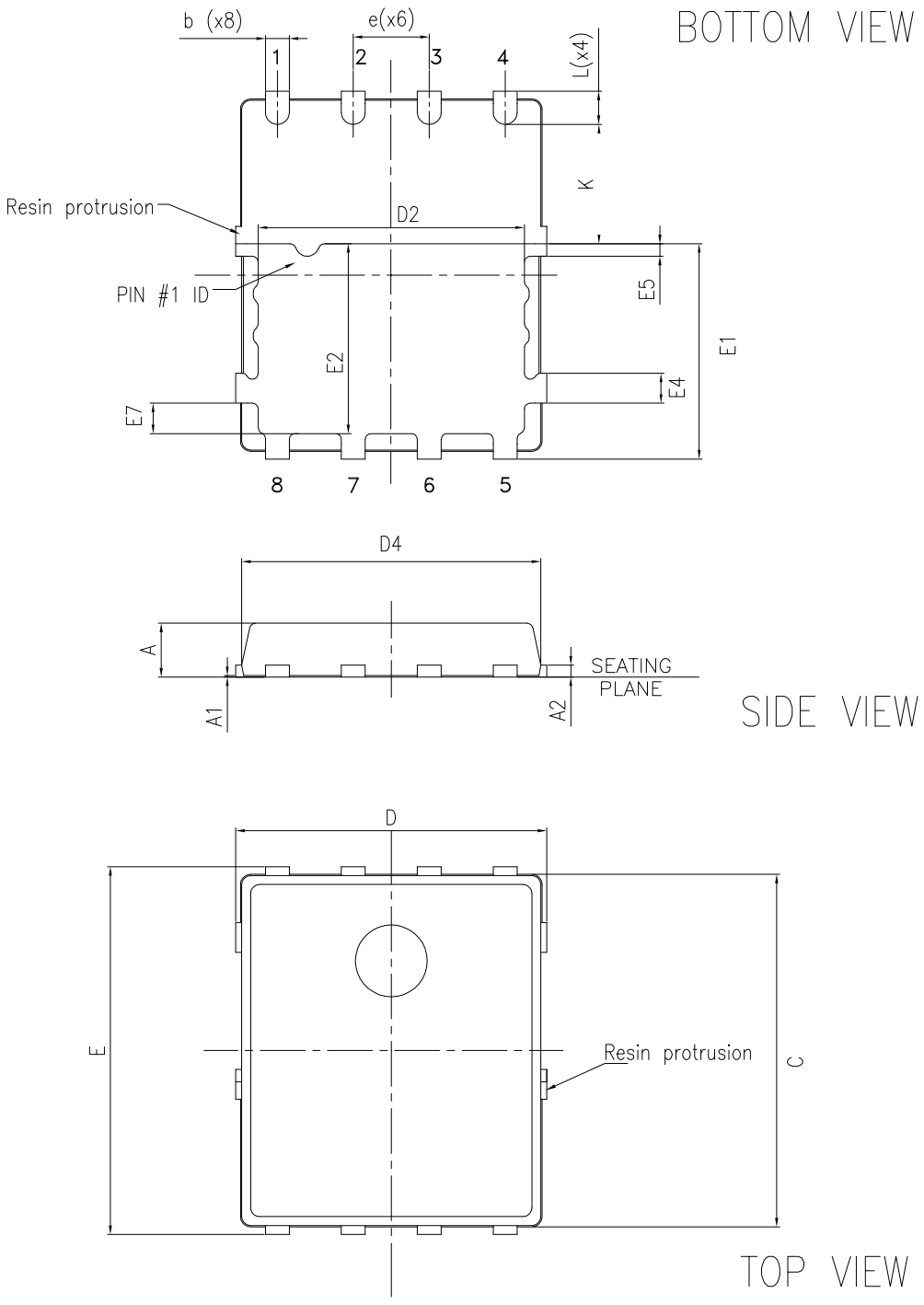


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 HV package information

Figure 19. **PowerFLAT™ 5x6 HV package outline**

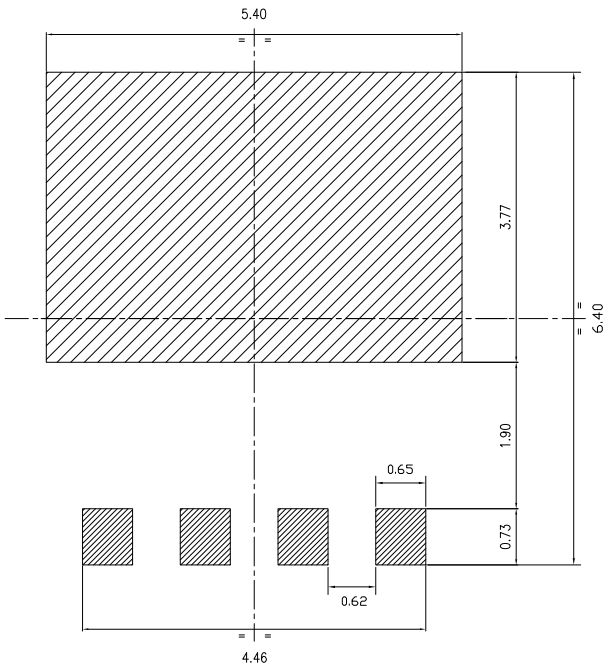


8368143_Rev_4

Table 7. **PowerFLAT™ 5x6 HV mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.60	5.80	6.00
D	5.10	5.20	5.30
D2	4.30	4.40	4.50
D4	4.60	4.80	5.00
E	6.05	6.15	6.25
E1	3.50	3.60	3.70
E2	3.10	3.20	3.30
E4	0.40	0.50	0.60
E5	0.10	0.20	0.30
E7	0.40	0.50	0.60
e		1.27	
L	0.50	0.55	0.60
K	1.90	2.00	2.10

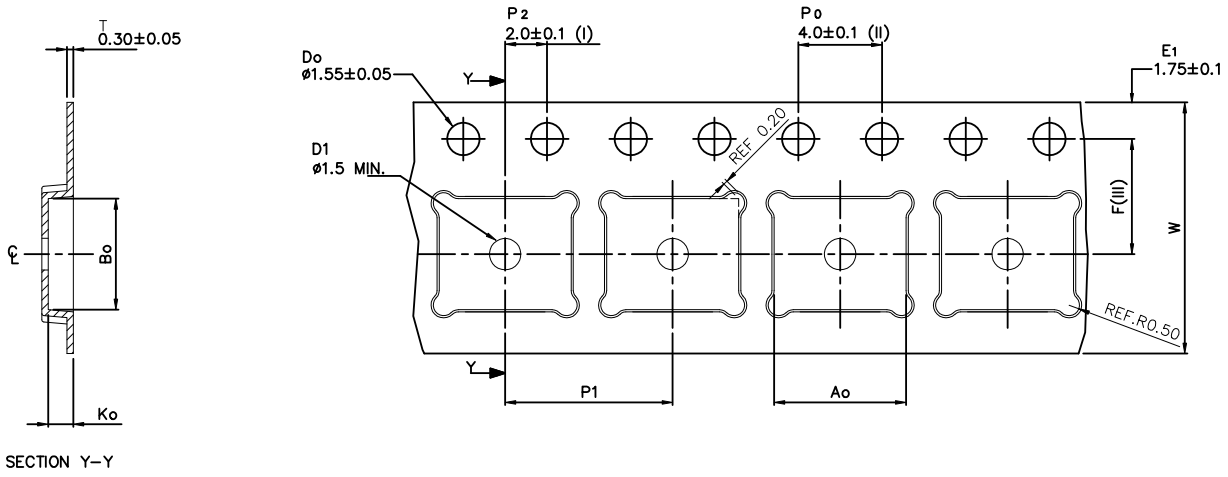
Figure 20. **PowerFLAT™ 5x6 HV recommended footprint (dimensions are in mm)**



8368143_Rev_4_footprint

4.2 PowerFLAT™ 5x6 packing information

Figure 21. **PowerFLAT™ 5x6 tape (dimensions are in mm)**



Ao	6.30 +/– 0.1
Bo	5.30 +/– 0.1
Ko	1.20 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

(I) Measured from centreline of sprocket hole to centreline of pocket.

(II) Cumulative tolerance of 10 sprocket holes is ±0.20.

(III) Measured from centreline of sprocket hole to centreline of pocket

Base and bulk quantity 3000 pcs
All dimensions are in millimeters

8234350_Tape_rev_C

Figure 22. **PowerFLAT™ 5x6 package orientation in carrier tape**

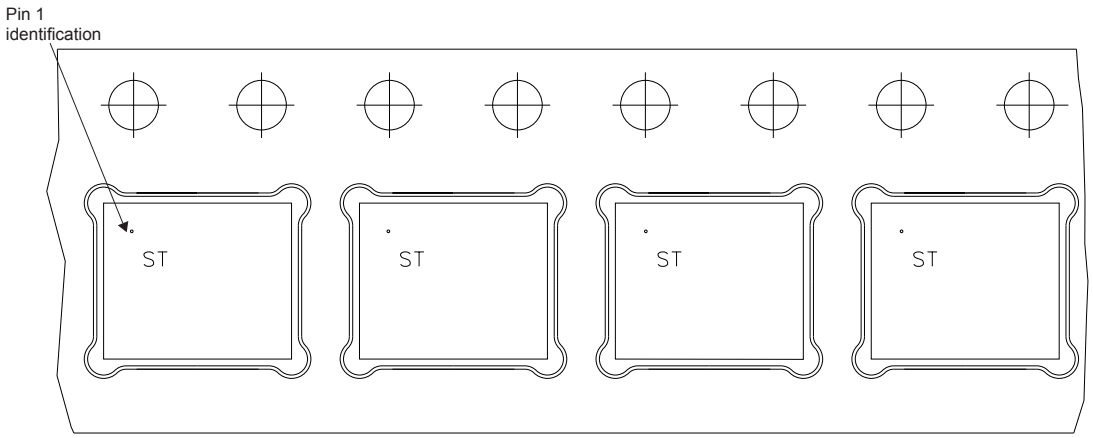
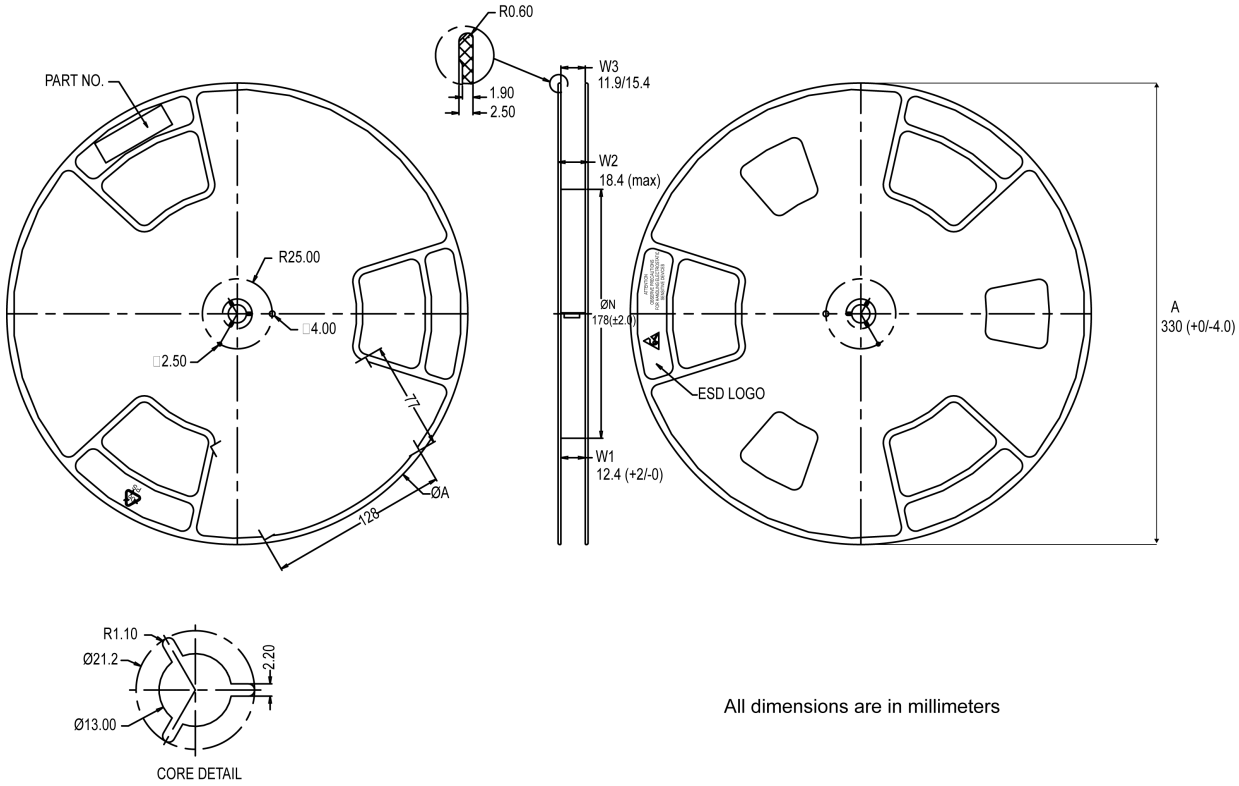


Figure 23. **PowerFLAT™ 5x6 reel**



All dimensions are in millimeters

8234350_Reel_rev_C

Revision history

Table 8. **Document revision history**

Date	Revision	Changes
13-Jan-2019	1	First release.

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4 **Package information** 8

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